Supporting Information

Processing of the P(NDI2OD-T2) Film without Intermediate Wetting Layer during the Spin-coating to Improve the Charge Carrier Mobility

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Supporting Information contents

Table S1. The film thickness at various substrate temperatures.

Table S2, S4-S6. Relationship between the substrate temperature and solvent evaporation rate in various solvents.

Table S3. The fibrous length and width.

Fig. S1. SAXS diffraction patterns of P(NDI2OD-T2) films.

Fig. S2. Transfer and output characteristic curves of different OFET devices.

Substrate temperature (°C)	Average film thickness (nm)
25	31±2
60	33±2
80	32±3
100	29±5
110	27±3

Table S1. The film thickness at various substrate temperatures.

Table S2. Relationship between substrate temperature and solventevaporation speed in p-Xylene (PX) solvent.

Solvent	Boiling point (°C)	Molar volume (ml mol ⁻¹)	Substrate temperature (°C)	Solvent evaporation speed (µm s ^{.1})
			25	6.4±0.2
			60	31.6±1.0
	PX 138 123.3		80	69.1±2.5
			90	98.0±3.5
DV		100.0	95	115.6±4.7
FX		138 123.3	98	129.0±5.3
			99	133.0±5.4
			100	137.0±5.6
			110	189.0±6.6
			120	257.5±9.1

Table S3. The fibrous length and width obtained by TEM.

Substrate temperature (°C)	Fibrous length (nm)	Fibrous length (nm)
25	90±14	4.2±1.5
60	113±19	5.6±1.9
80	145±26	7.1±2.4
100	185±27	9.8±3.8
110	187±32	11.6±4.6

Table S4.	Relationship	between	the	substrate	temperature	and	solvent
evaporatio	n speed in o-X	Xylene (O	X) s	olvent.			

Solvent	Boiling point (°C)	Molar volume (ml mol ^{.1})	Substrate temperature (°C)	Solvent evaporation speed (μm s ⁻¹)
			25	5.3±0.2
			60	26.8±1.1
	OX 143 123.3		80	59.1±2.5
			90	84.8±3.4
OY		102.2	95	100.5±4.1
UX.		123.3	100	117.9±4.8
			103	131.6±5.4
			105	139.8±5.7
			110	165.7±6.7
			120	225.9±9.2

Table S5. Relationship between the substrate temperature and solventevaporation speed in m-Xylene (MX) solvent.

Solvent	Boiling point (°C)	Molar volume (ml mol ⁻¹)	Substrate temperature (°C)	Solvent evaporation speed (µm s ^{.1})
		25	6.2±0.2	
	MX 139 123.3		60	30.6±1.2
			80	66.7±2.7
			90	94.6±3.9
MX		123.3	95	113.3±4.6
			100	133.0±5.4
		105	157.6±6.4	
		110	184.9±7.6	
		120	249.6±10.2	

Solvent	Boiling point (°C)	Molar volume (ml mol ^{.1})	Substrate temperature (°C)	Solvent evaporation speed (µm s ^{.1})
	Tol 111 105.9		25	14.2±0.5
		40	29.1±1.2	
			60	63.4±2.6
Tal		105.0	80	131.6±5.4
101		111 105.9	81	135.6±5.6
		85	156.0±6.4	
		90	181.3±7.4	
			100	252.1±10.3

Table S6. Relationship between the substrate temperature and solventevaporation speed in toluene (Tol) solvent.

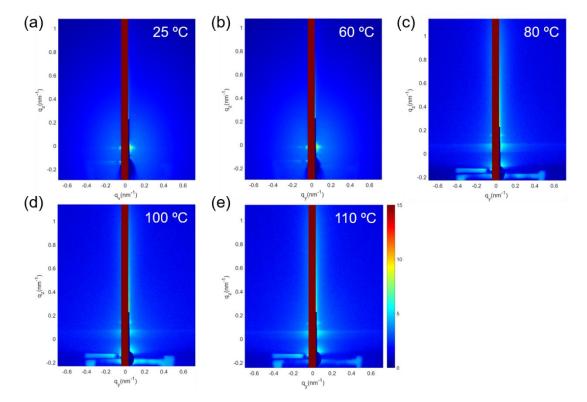


Fig. S1 SAXS diffraction patterns of P(NDI2OD-T2) films at different substrate temperatures.

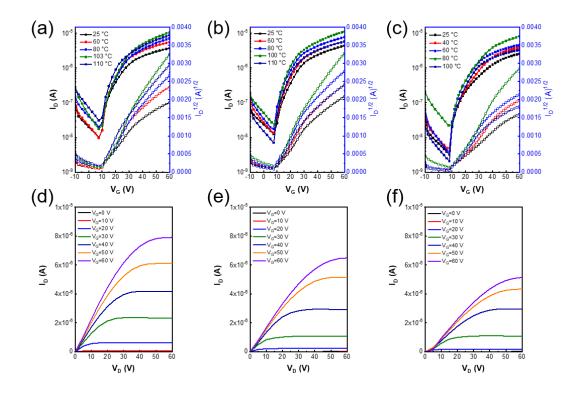


Fig. S2 Transfer and output characteristic curves of OFETs devices with P(NDI2OD-T2) film under different film formation conditions (a, d) OX, (b, e) MX, and (c, f) Tol, respectively.